

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHENG-KAI HUNG	08/11/2020
TSAI-CHIN CHENG	08/11/2020
YI-KUAN WU	08/11/2020
PING-HSIUNG CHIU	08/11/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	REALTEK SEMICONDUCTOR CORPORATION
<b>Street Address:</b>	NO. 2, INNOVATION ROAD II, HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	Taiwan ROC
<b>Postal Code:</b>	300
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17102469
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<b>SIGNATURE:</b>	/Justin King/
<b>DATE SIGNED:</b>	11/24/2020
<b>Total Attachments: 2</b>	
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**ASSIGNMENT**

WHEREAS, I(we), SHENG-KAI HUNG, TSAI-CHIN CHENG, YI-KUAN WU and PING-HSIUNG CHIU whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled.

**Universal profiling device and method**

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

- ☐ United States Design Patent was  
☐ executed on:  
☐ filed on: Serial No.:  
☐ established by PCT International Patent Application No.: filed: designating the  
 United States of America  
☐ issued on \_\_\_\_\_ as U.S. Patent No.: \_\_\_\_\_

WHEREAS, **REALTEK SEMICONDUCTOR CORPORATION** whose post office address is **No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)** hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR NAME <b>SHENG-KAI HUNG</b>	Address No. 2, Innovation Rd. II Hsinchu Science Park Hsinchu 300, Taiwan
Signature of Assignor <i>Sheng-kai hung</i>	Date of Signature <b>August 11, 2020</b>
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME TSAI-CHIN CHENG	Address No. 2, Innovation Rd. II Hsinchu Science Park Hsinchu 300, Taiwan
Signature of Assignor TSAI CHIN CHENG	Date of Signature August 11, 2020
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME YI-KUAN WU	Address No. 2, Innovation Rd. II Hsinchu Science Park Hsinchu 300, Taiwan
Signature of Assignor YI KUAN WU	Date of Signature August 11, 2020
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME PING-HSIUNG CHIU	Address No. 2, Innovation Rd. II Hsinchu Science Park Hsinchu 300, Taiwan
Signature of Assignor Ping Hsiung Chiu	Date of Signature August 11, 2020
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)